

Realizing IOWN 2.0 : Development Status and Future Outlook of Opto-Electronics Convergence Network Switches

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Challenging the World with IOWN and Optical Communication

Effectively No Distance

IOWN 1.0 (PEC-1)



Solving Power Issues in Data Centers

IOWN 2.0 (PEC-2)

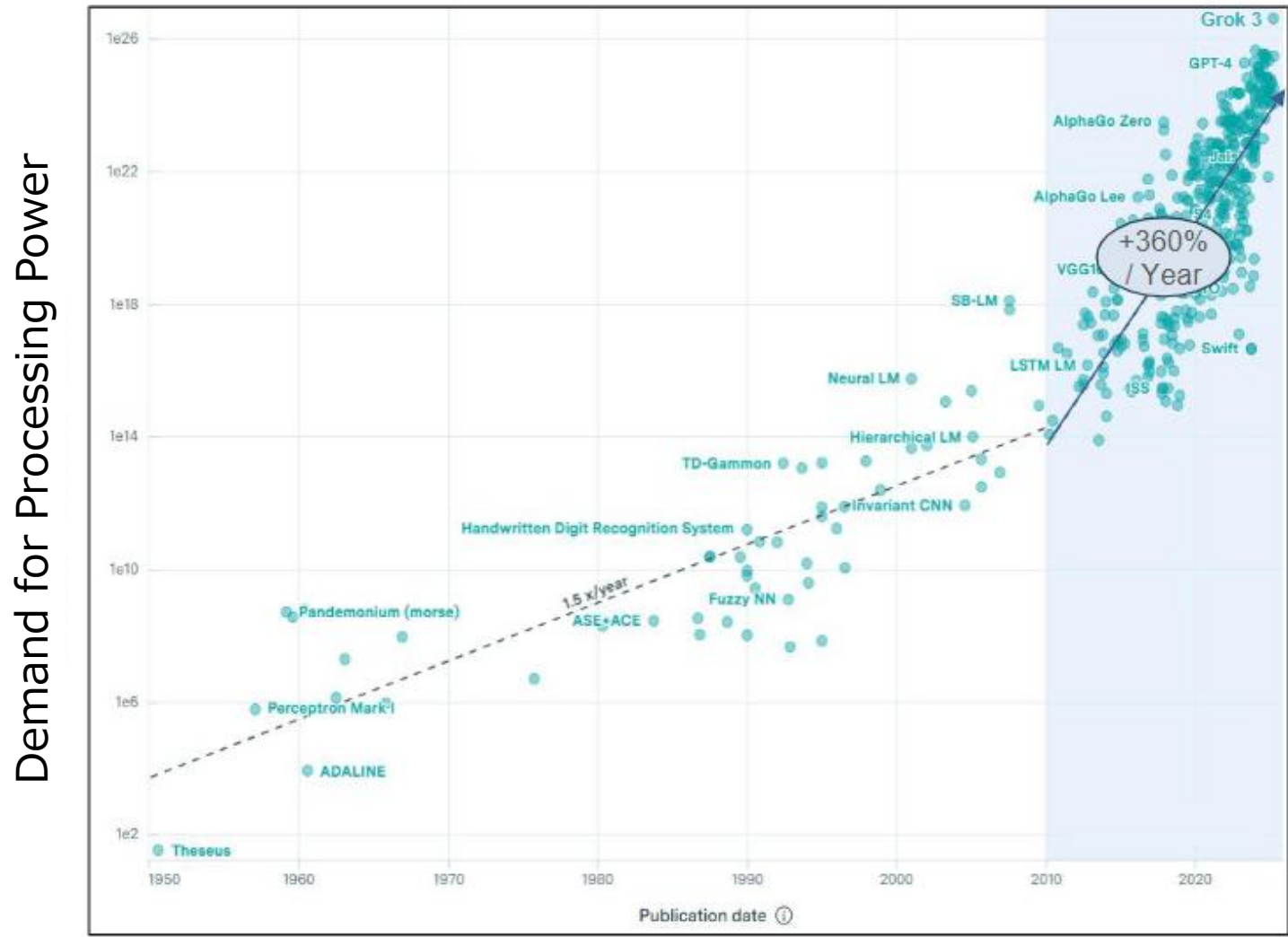




	Legacy cloud services	AI (e.g. LLM)
Tasks	Relatively small	Huge
Server (processor)	With one processor shared across multiple tasks	To do one task, 1000 + processors
Key Technology	Virtualization	Between processors communication network

Accelerating need for **optical** links
between processors

AI : The Tilt for Computational Performance



Directions for Surging AI Demand

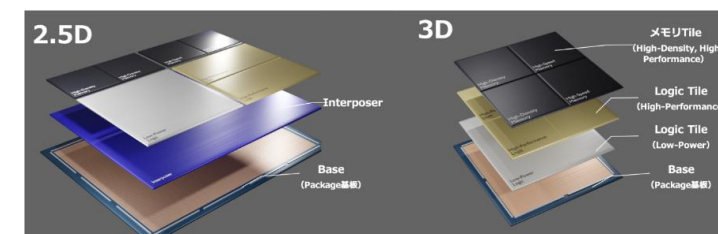
Three Pillars of Semiconductors

Advanced Semiconductor Miniaturization

Pushing Miniaturization to the Limit
(7nm → 5nm → 3nm → 2nm → Sub2nm → Å)

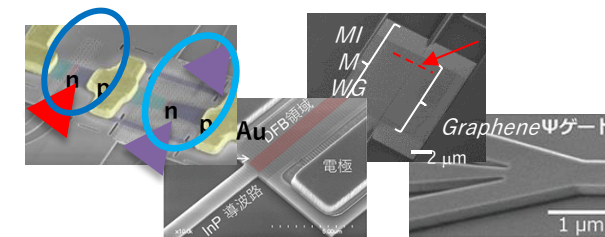
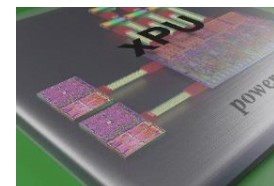
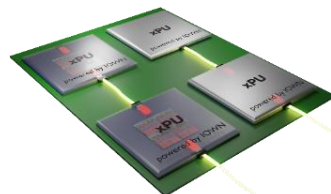
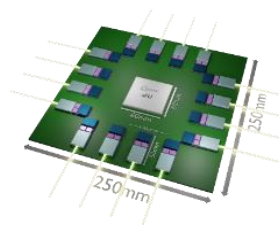
Ultra-Dense Packaging

Planar integration is reaching its limits
— shifting toward 2.5D and 3D packaging



Opto-Electronic Integration

Limits of electrical technology (bandwidth + power)
➡ Opto-Electronic Convergence ➡ Partial replacement by photonics in the future
Application of optical communication technology expands from networking to **networking + computing**



Advanced Semiconductor Miniaturization

The Limits of Moore's Law

- Moore's Law: **The integration rate of semiconductor integrated circuits doubles every 18 months (later, every 24 months).**
- When a circuit is miniaturized to $1/k$, the area becomes $1/k^2$, the power consumption becomes $1/k^2$, and the performance per unit area becomes k^2 .
 - ➔ This supports strong demand for semiconductors.
- However, it has become increasingly difficult to improve performance through conventional scaling.**

• Limit of miniaturization

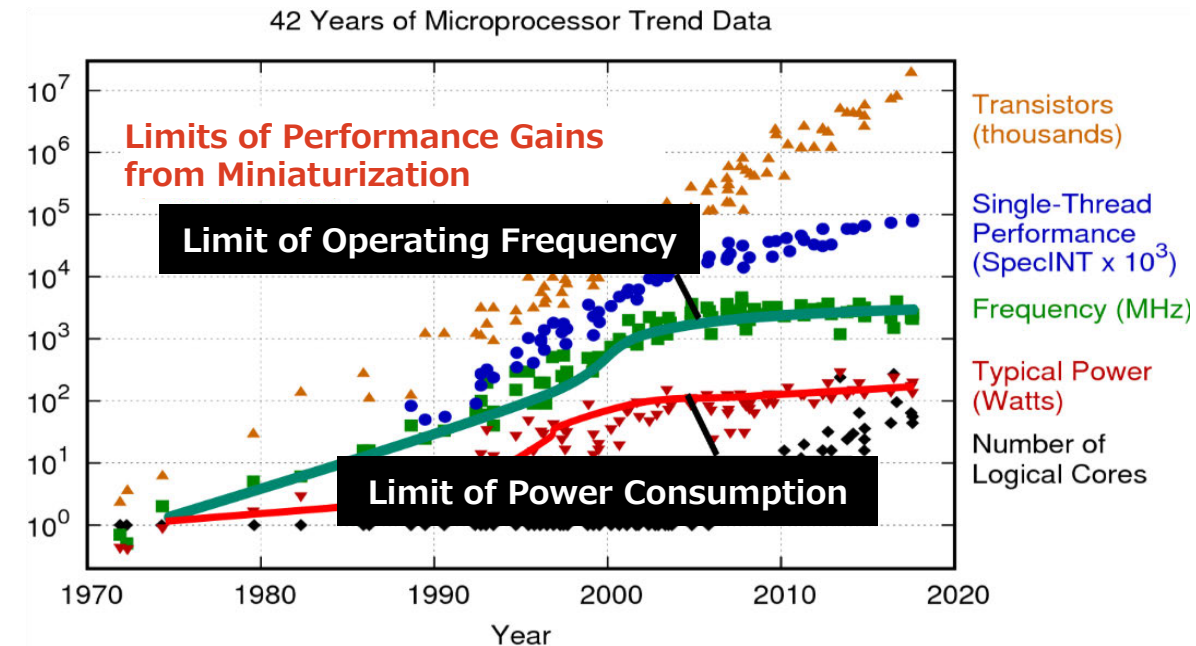
- Get closer to the atomic size.
- The influence of leakage current cannot be ignored.

• Limit of heat generation

- Increased internal resistance due to heat generation -> Further fever
- Increase in leakage current due to heat generation
- Cannot raise the operating frequency.

• Power consumption limit

- Increased power consumption
- > Performance degradation due to heat generation (dark silicon)

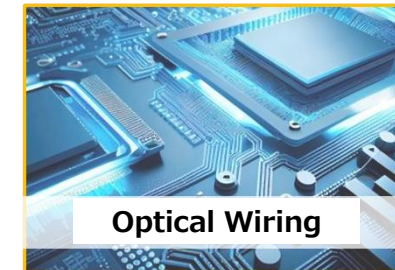
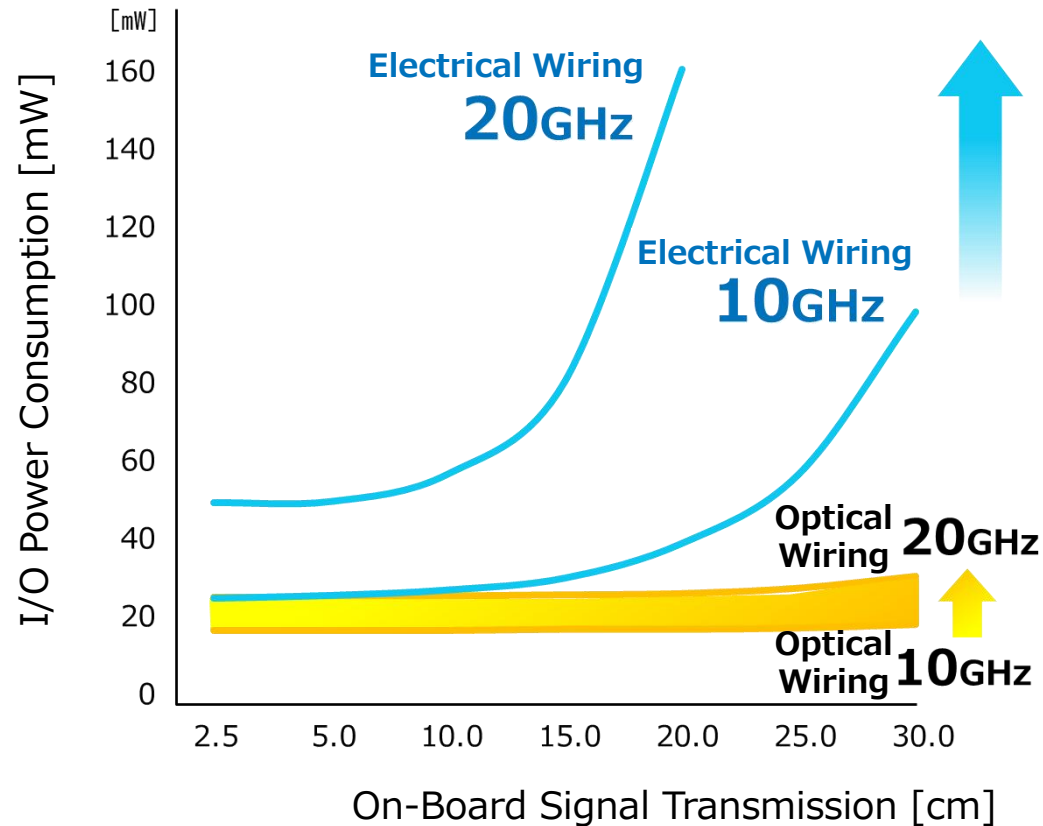


出典: <https://www.karlsruhe.net/2018/02/42-years-of-microprocessor-trend-data/>

The Road to High Frequency and Low Power

Toward Opto-Electronic Convergence

50~100 GHz is already in practical use

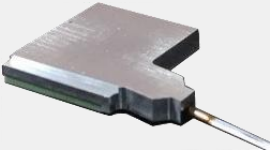

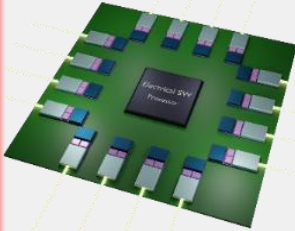
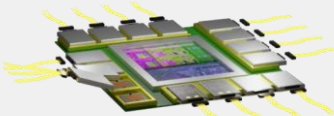

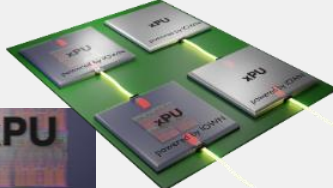



Optical signals are reaching deep into data centers, servers, and even semiconductor chips!

Evolution of Opto-Electronic Devices

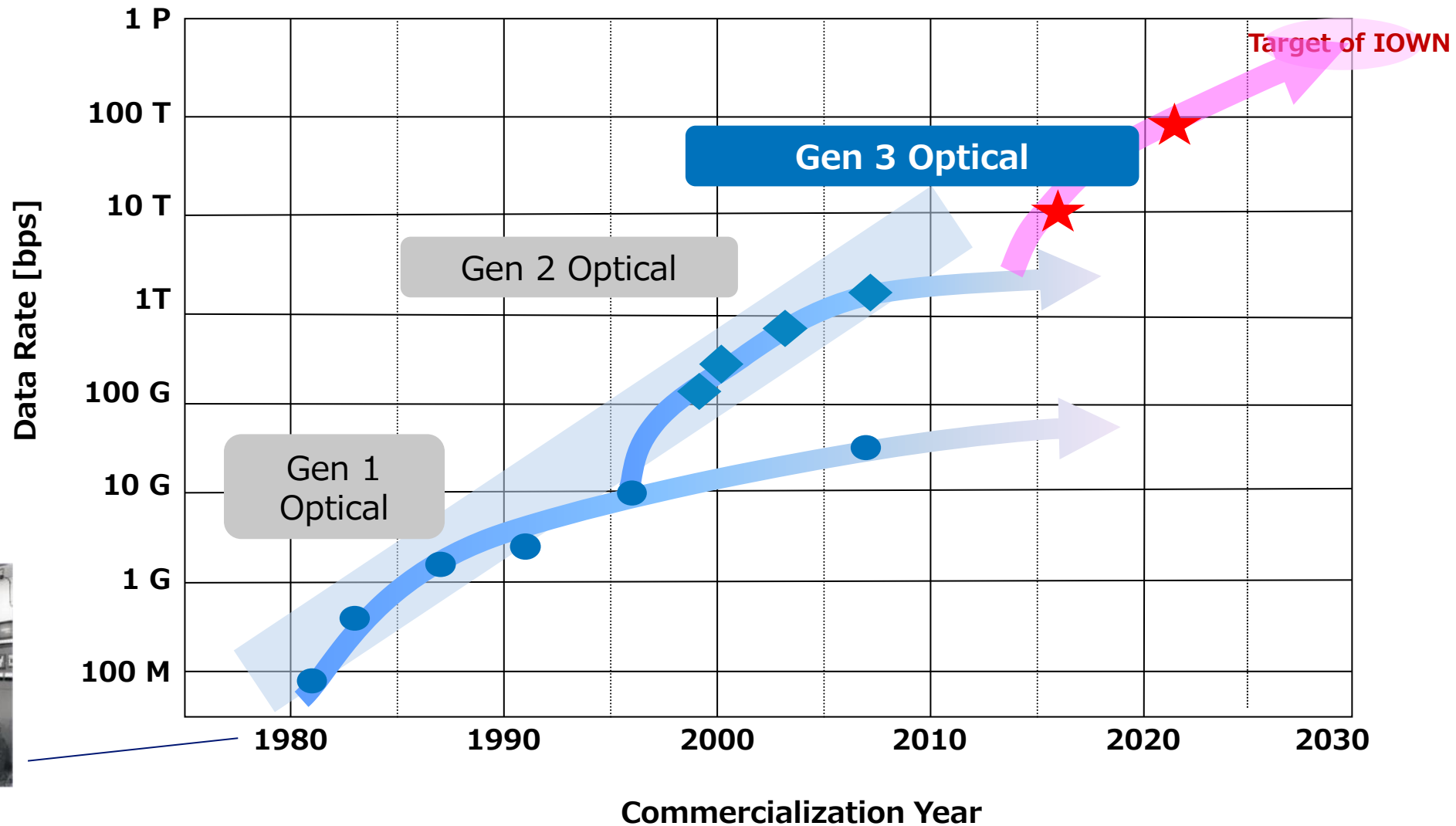
Roadmap

PEC : Photonics Electronics Convergence

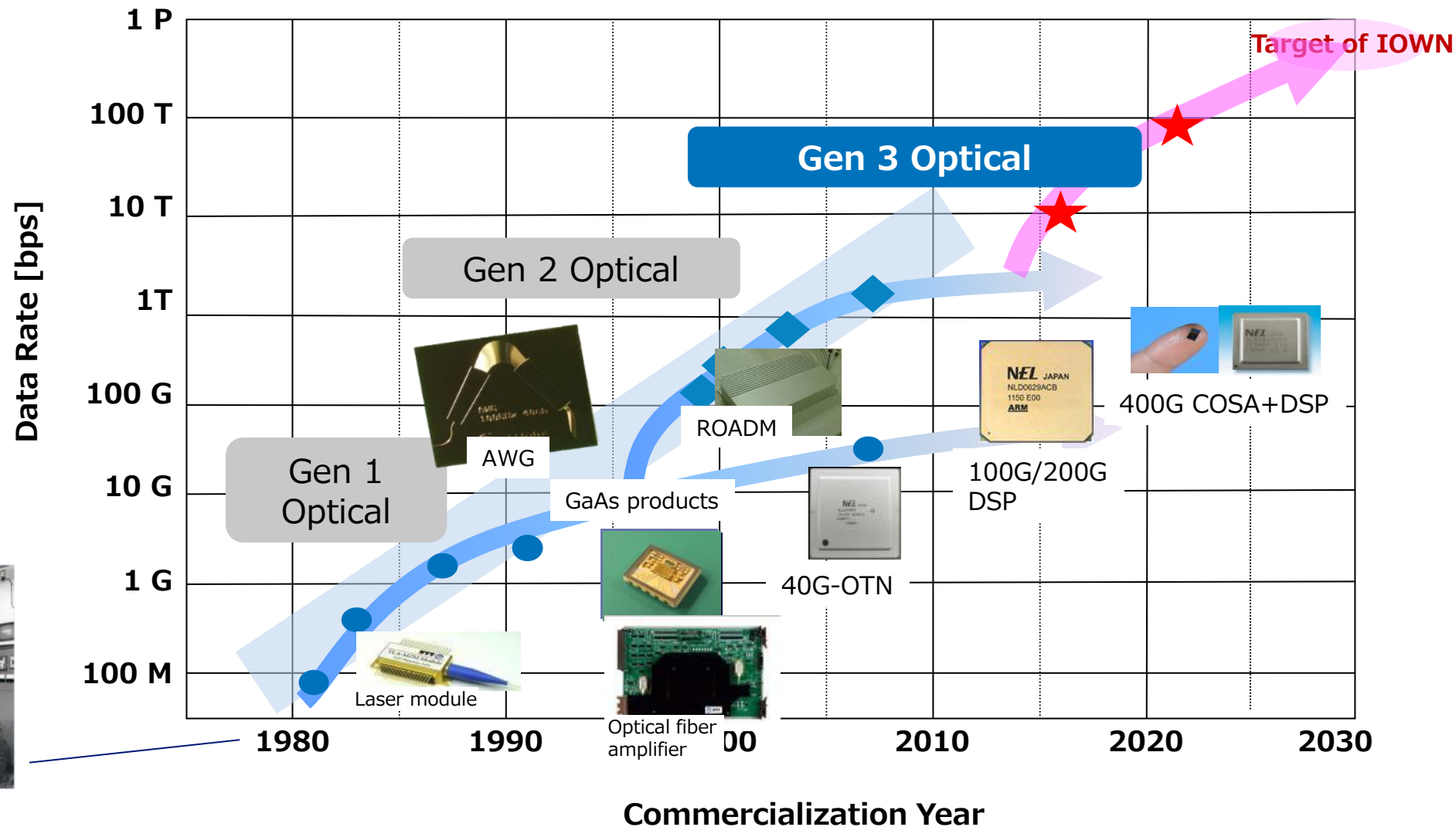
Commercialization	CY2021	CY2023	CY2025 – CY2026	CY2028	CY2032
Generation	PEC-1 DC to DC		PEC-2 Board to Board	PEC-3 Package to Package	PEC-4 Die to Die
Data-rate /Device	400G->800G->1.6T->3.2T->		1.6T->3.2T->6.4T->	64G->128G->	
Business Domain	Telecom	Telecom	Computing	Computing	Computing
Images	 COSA	 CoPKG	  CY25:LFF CY26:AFF	  xPU xPU	
Distance	1000km	100km	10m	~cm	~mm

increase in shipment

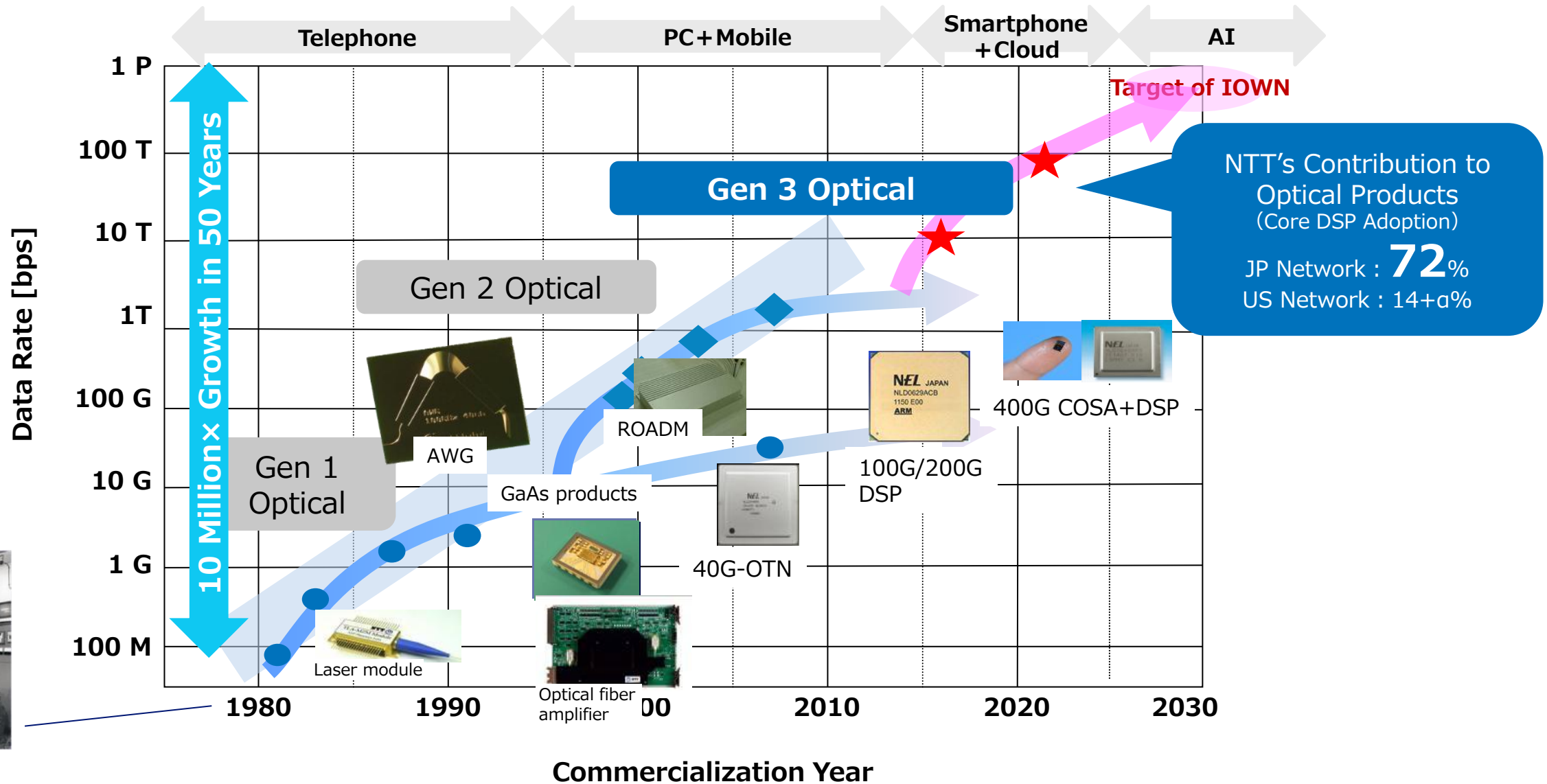
NTT and the History of Optical Innovation



NTT and the History of Optical Innovation

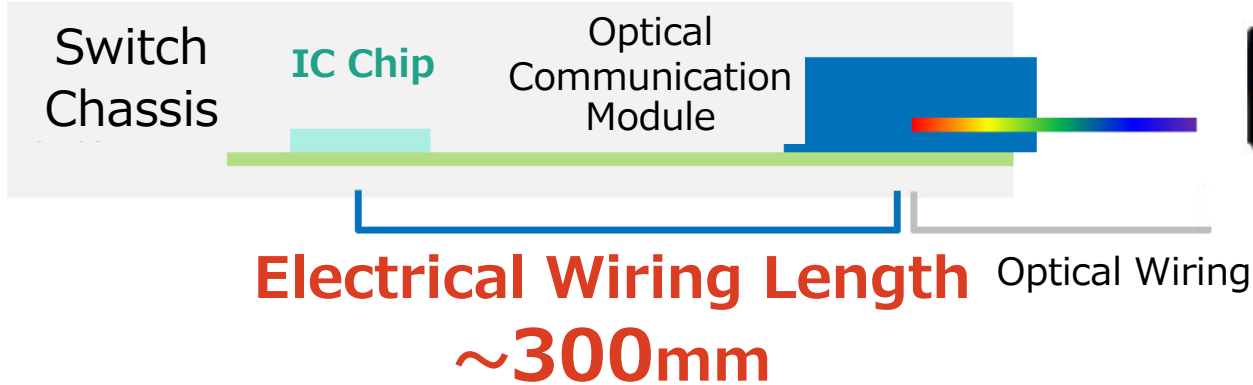


NTT and the History of Optical Innovation



Opto-Electronic Switch Overview

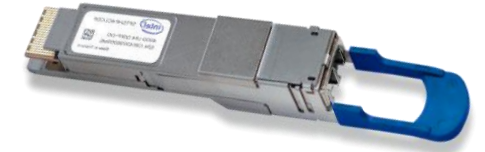
Conventional Optical Communication Switch



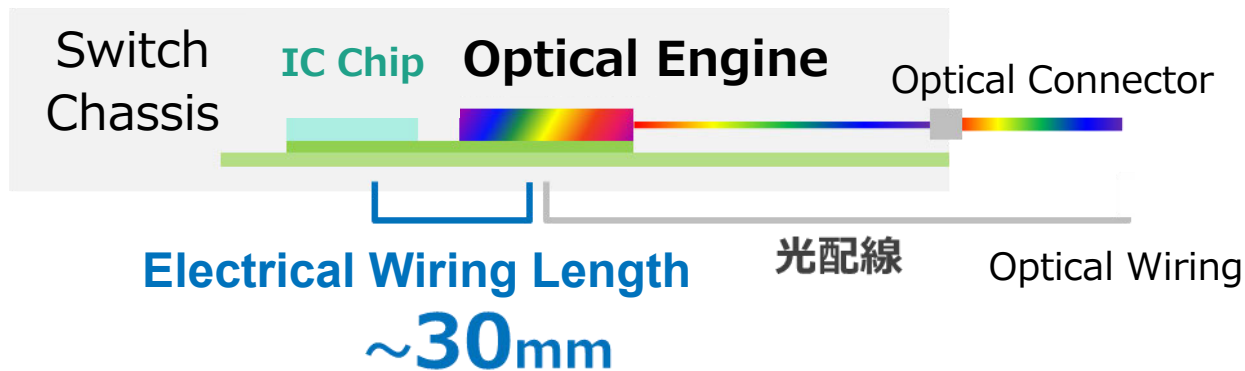
Front View



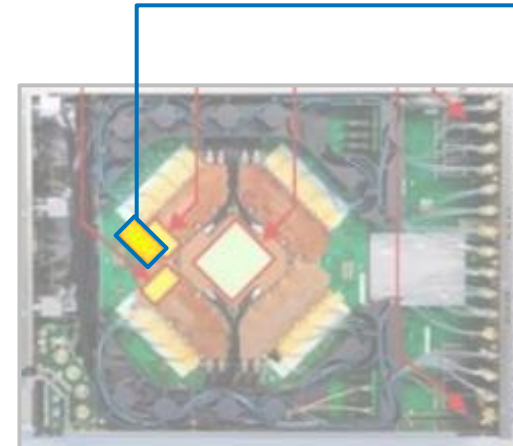
Insertion Port for Optical Communication Module



Opto-Electronic Converged Switch



Top View

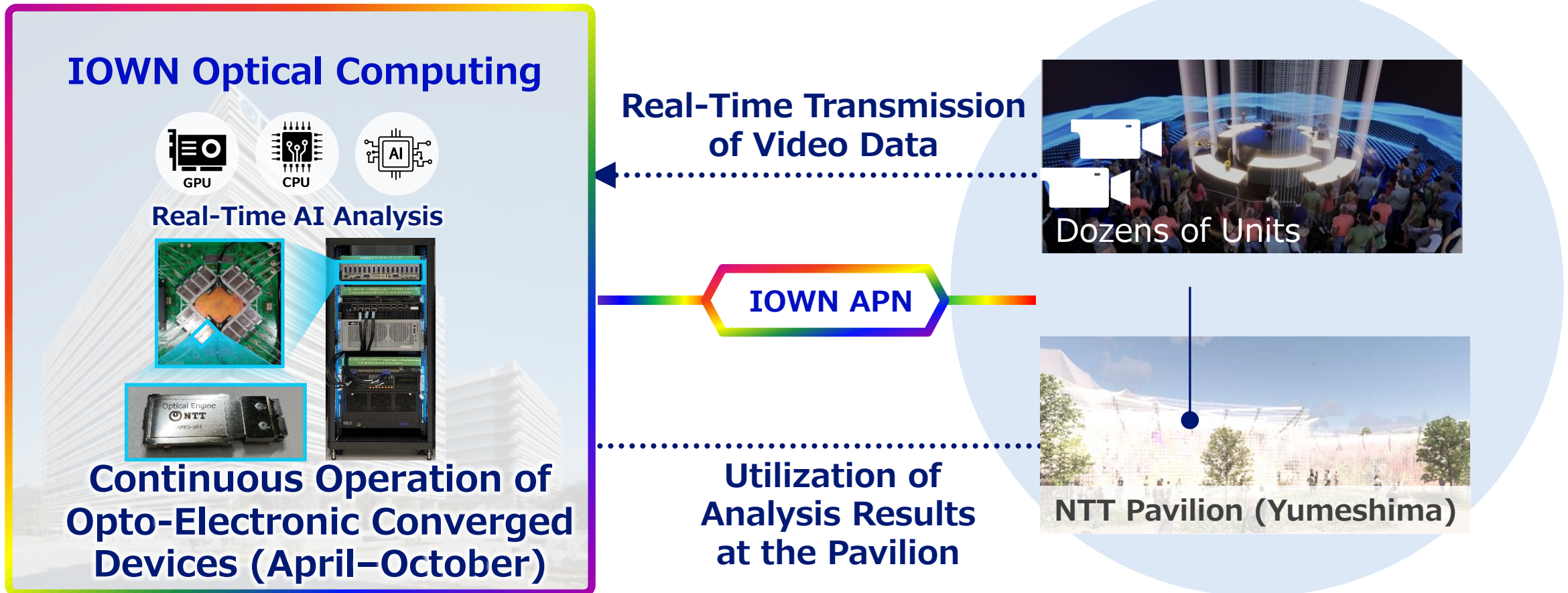


Optical Engine

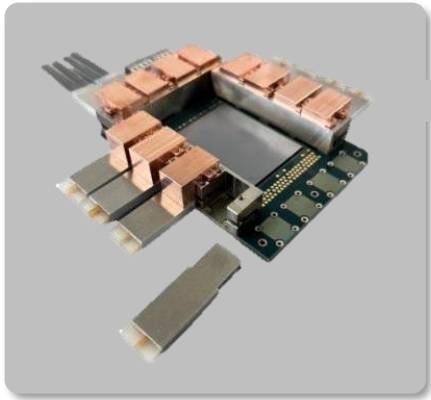
(Opto-Electronic Converged Device PEC-2)

Optical Computing at the Expo Pavilion

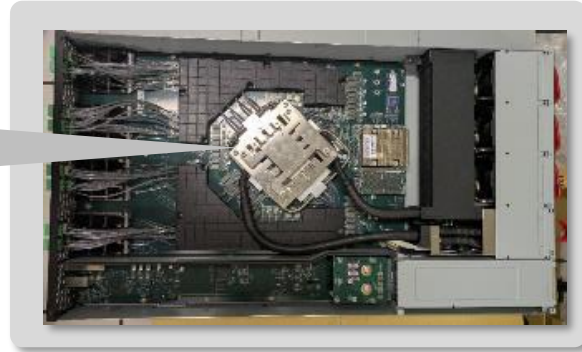
- At the NTT Pavilion of the Osaka-Kansai Expo, a computer powered by IOWN 2.0 achieved one-eighth the power consumption.
- This remarkable efficiency was made possible by a **combination** of **advanced devices, computer architecture, and software**.



Commercial Deployment of Opto-Electronic Converged Switches



NID Products
"6.4T Optical engine &
102.4T CPO-SW Module"



System Partner Products
"102.4T SW-BOX"



System Partner Products
"Switch Rack"



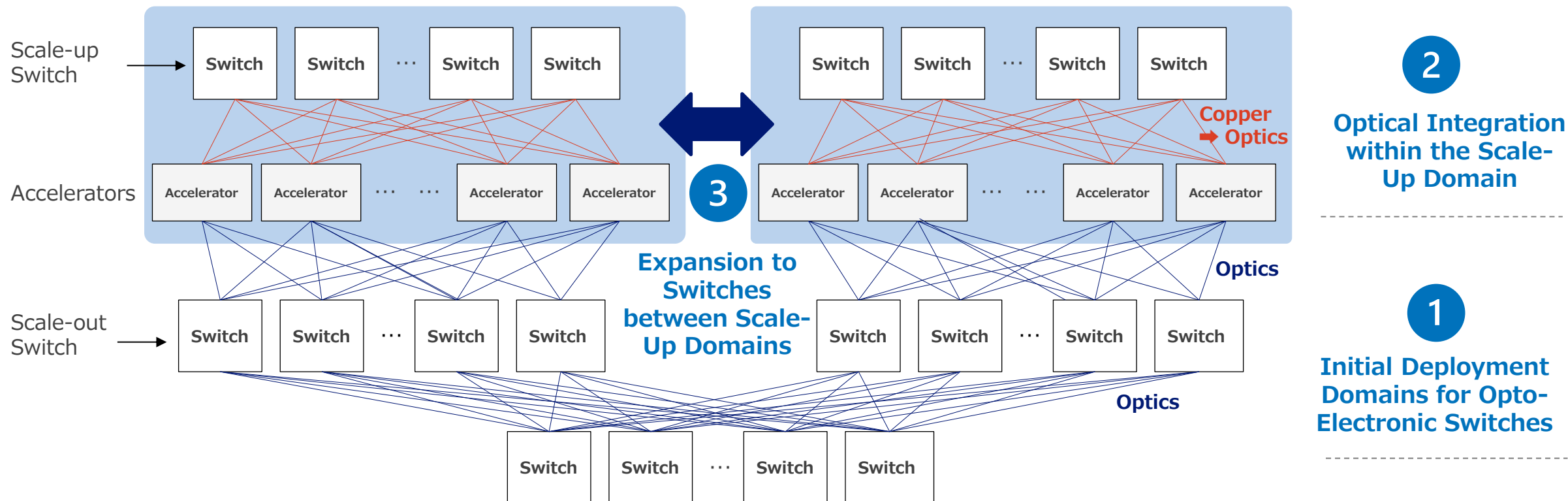
**Server-to-Server
Interconnection within a
Data Center**

- **Commercialization Target: Q4 2026 (Sample Release)**
- Verification of Component Characteristics in Progress
- Significant Power Reduction, High-Capacity Switch, and Lower Repair & Operational Costs through Replaceable Optical Engines
- Expansion of Manufacturing Capacity Underway (5,000 Units per Line per Month)



**Prototype Switch with
51.2 Tbps Capacity**

Data Center Switch Architecture & Opto-Electronic Switch Deployment



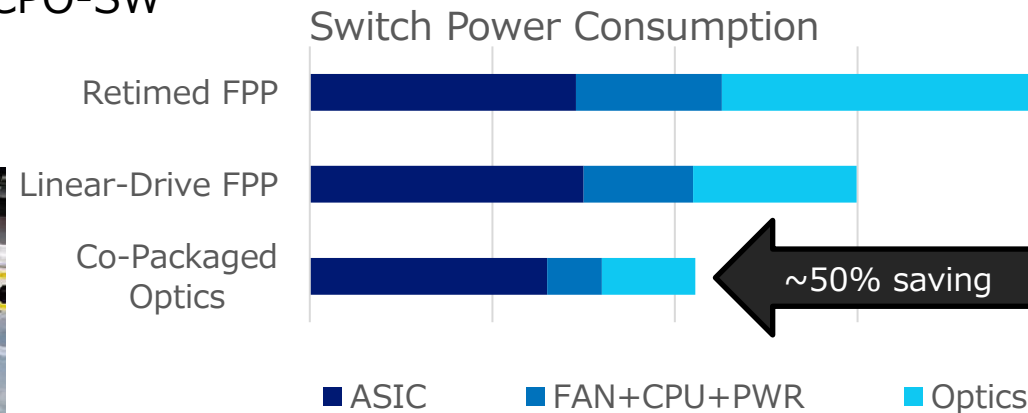
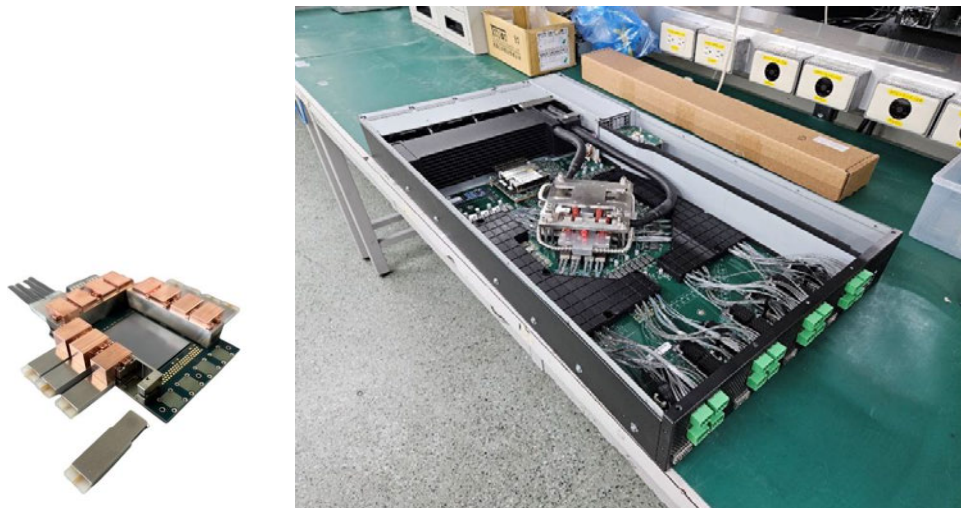
Candidate Domains for the Introduction of Opto-Electronic Converged Switches:

1. Initial deployment in the Scale-Out domain
2. Optical integration within the Scale-Up domain
3. Potential expansion to inter-Scale-Up domain switches

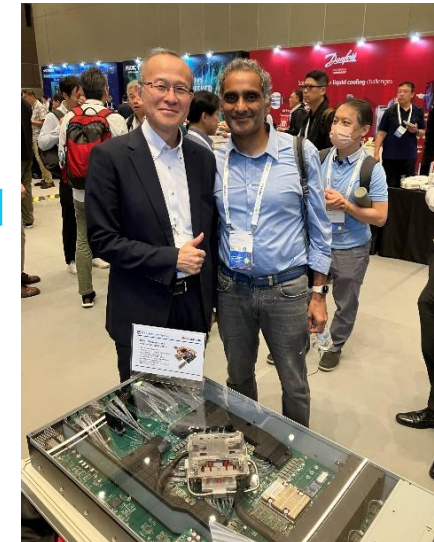
PEC-2

Commercial Deployment of Opto-Electronic Converged Switches

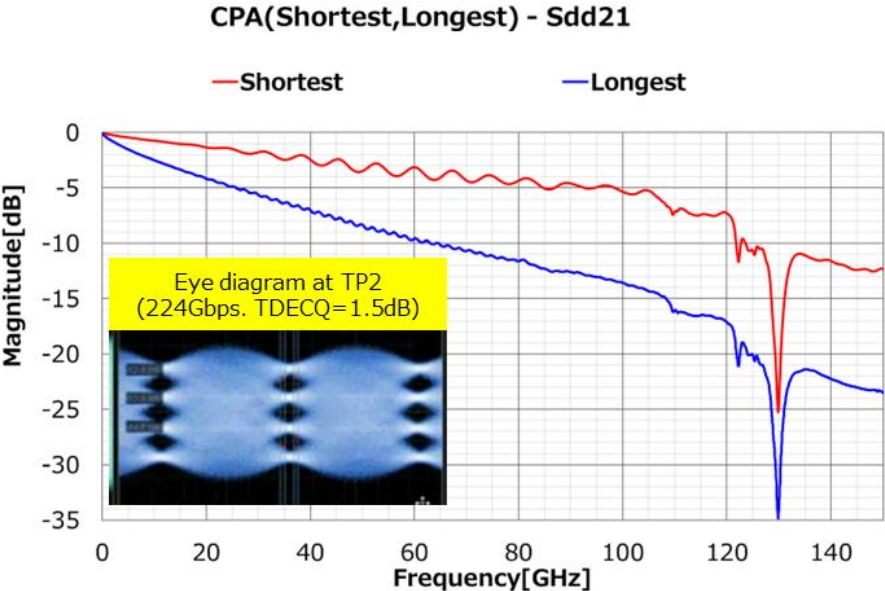
- 102.4 Tbps Capacity, 50% Power Reduction with Switch Alone
- Partnership Established: Broadcom + Accton
- Market Launch Starting in 2026
 - 2026 Q2: Optical Engine Samples
 - 2026 Q3: Live Demonstration at OCP 2026
 - 2026 Q4: Commercial Samples of CPO-SW





BROADCOM



- **A Unique Socket-type Optical Engine**
 - Enables fundamental reduction in repair costs in case of optical engine failure
 - Flexibly supports media mix (short-reach, long-reach, wavelength-division multiplexing, etc.) and evolving data center configuration
 - A multi-vendor supply chain is also being considered for future scalability
- **Target Performance Metrics for Opto-Electronic Convergence**
 - **3.9pJ/b** power efficiency
 - **0.4Tbps/mm** shoreline density




		Optical Connection Types	
		Fiber	Connector
Electrical Connection Types	Soldering		
	Socket		

Partner List

NTT Innovative Devices is responsible for the overall design of the CPO-SW module, and a coordination of the entire process including an alignment of partner companies to deliver the product.


Manufacture of the substrate
Assembly of CPO-SW module

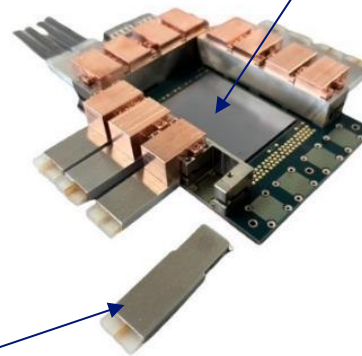
 **NTT Innovative Devices**
Design & assembly of 6.4Tbps
Optical engine

 **NTT Innovative Devices**
  Subsidiaries of
NTT Innovative Devices

Design and delivery of Photonic IC
and Electronic IC



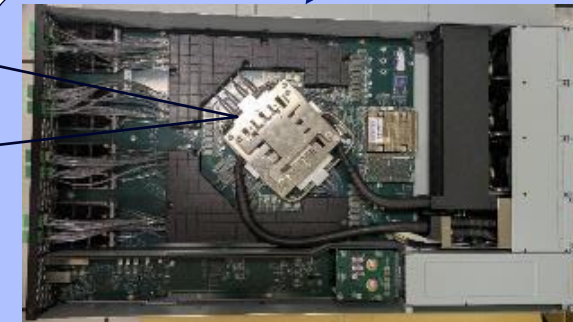
Design & delivery of
102.4Tbps SW-LSI



Products of NTT Innovative
Devices
"102.4T CPO-SW module &
6.4T Optical engine"



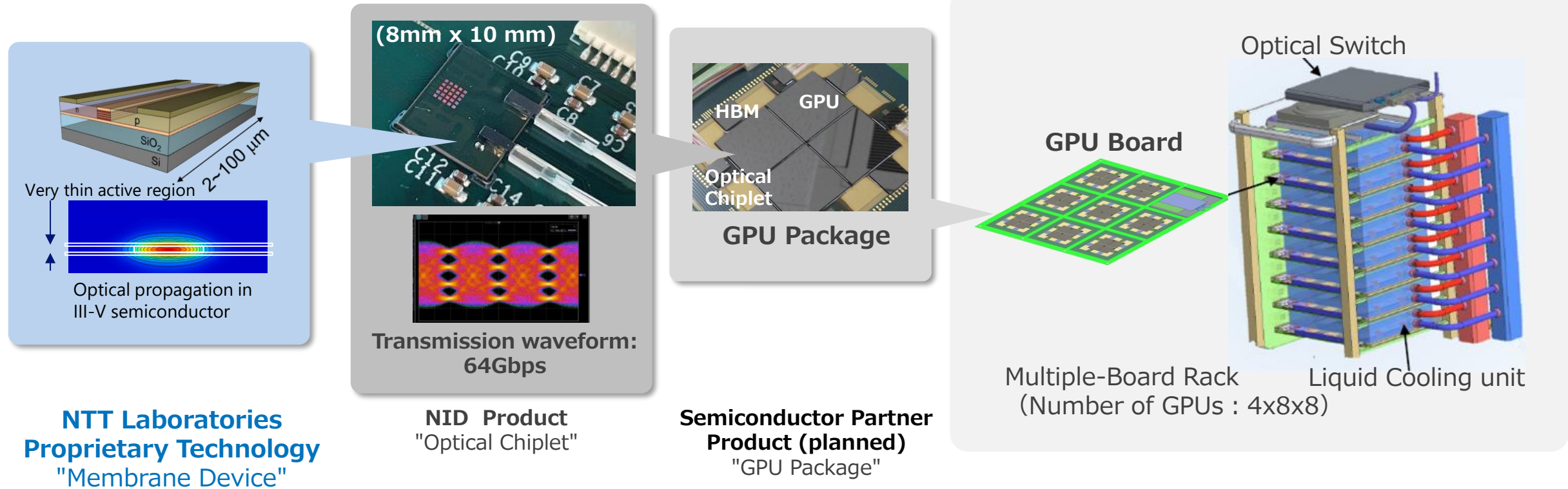
Design & manufacture of
102.4Tbps SW-BOX



Product of system partner
"102.4T SW-BOX"

PEC-3 (Next-Generation)

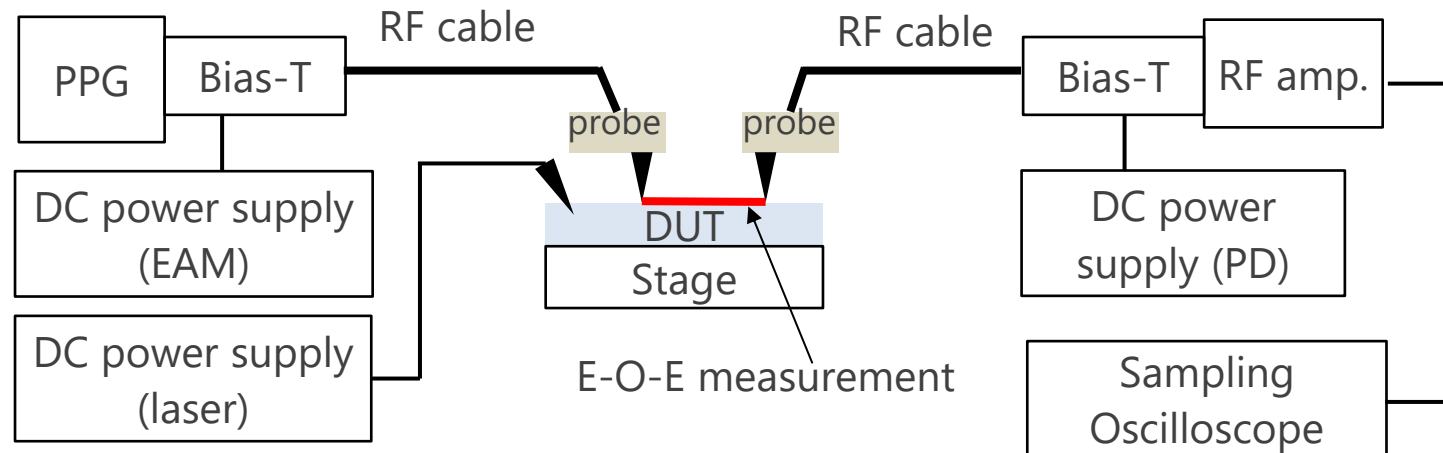
Chip-to-Chip Optical Interconnect (Optical Chiplet)



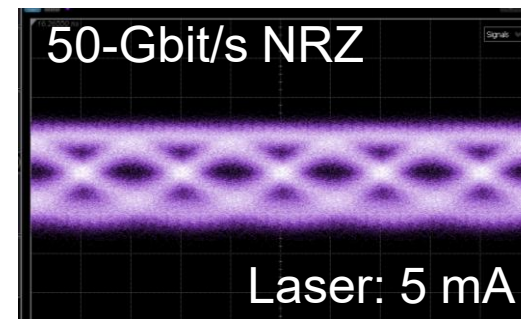
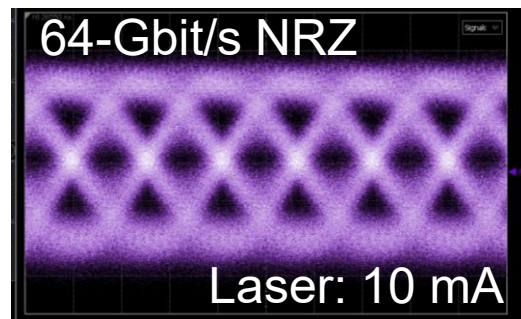
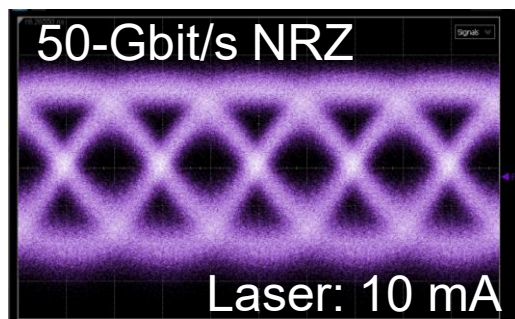
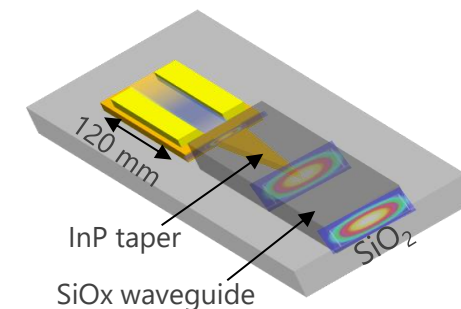
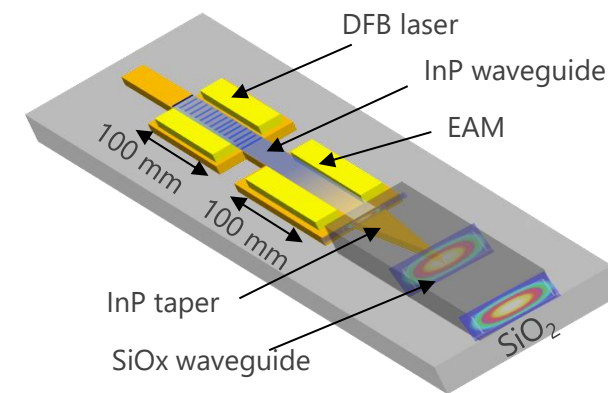
- **Commercial sample scheduled for Q4 2028**
- Evaluation with prototype in progress
- Ambitious target for further drastic power reduction: $\sim 0.26\text{pJ/bit}$

Feasibility check 0.26 pJ/bit Demonstration

DUT: Device under test



Experimental setup



Measured eye diagrams for NRZ signals

0.26 pJ/bit
for 64 Gbps @ 10 mA
0.14 pJ/bit
for 50 Gbps @ 5 mA

As AI becomes mainstream, connecting vast numbers of processors through networks is essential.

For low-power connections, optical communication is virtually the only viable solution.

NTT will continue to leverage its extensive experience in optical communications to take on global challenges.

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